TO263-6L

1、封装结构：

TO263-6L 采用表面贴装设计，具有 6 个引脚，其中包含一个用于散热的金属底座（Tab）。这种封装通过底部焊盘与 PCB 直接连接，实现良好的散热性能，适用于大电流、高功率的应用场景。

1. Package Structure

The TO263-6L adopts a surface-mount design with 6 pins, including a metal tab for heat dissipation. This package connects directly to the PCB via the bottom pad, delivering excellent thermal performance and making it suitable for high-current, high-power applications.

2、散热性能：

金属底座直接与 PCB 接触，可有效降低热阻，提高散热效率，适合处理较高功率的电路，如工业电源、电动汽车充电器、光伏逆变器等。

2. Thermal Performance

The metal tab makes direct contact with the PCB, which can effectively reduce thermal resistance and improve heat dissipation efficiency. It is suitable for high-power circuits such as industrial power supplies, electric vehicle chargers, and photovoltaic inverters.

3、电气特性：

支持较高的电流承载能力(通常可达数十安培)，并能承受一定的电压应力，常用于中高压(如 40V-1200V)功率转换电路。

3. Electrical Characteristics

It supports a high current-carrying capacity (typically up to several tens of amperes) and can withstand a certain level of voltage stress, making it ideal for medium-to-high voltage (e.g., 40V–1200V) power conversion circuits.

4、应用领域：

广泛应用于电源管理、电机驱动、新能源汽车、工业自动化等领域，尤其适用于需要紧凑布局和高效散热的场景。

4. Application Fields

It is widely used in fields such as power management, motor drive, new energy vehicles, and industrial automation, and is particularly suitable for scenarios requiring compact layout and

high-efficiency heat dissipation.